

International Forum on Powder Technology & Application

(Beijing, 30 to 31, March, 2009)

Main Topics

New Materials, Resources Exploitation and Energy Saving

Place: Tsinghua University, Beijing

Language: English and Chinese

Co-events:

2009 National Conference on Powder Processing and Application

China International Powder Technology & Equipment Exhibition

China International Industrial Powder Raw Materials Exhibition

Date: 1 to 3, April, 2009

Place: Beijing Exhibition Center

Organization of the Forum

Chairman:

Prof. Delong Xu, the member of Chinese Academy of Engineering

Vice Chairman:

Prof. and President, Hitoshi Emi, the Association of Powder Processing Industry & Engineering, Japan

Prof. and Director, Julie Chen, Nanomanufacturing Center of Excellence, UMass, USA

Prof. and President, Yongmo Xu, China Powder Technology Association

Secretary:

Prof. Guosheng Gai, Research Institute of Powder Technology, Tsinghua University

Academic committee members

Allan Guo (US)	Chen-Chi M.Ma, (Taiwan, China)	D. Nikolaas (Belgium)
David R. Buchanan (US)	Duan Weng (China)	Feiyu Kang (China)
Fengsheng Li (China)	Fumio Saito (Japan)	Fu-Su Yen (Taiwan, China)
Gary Liu (US)	Heechan Cho (Korea)	Hiroyuki Kage (Japan)
Hitoshi Emi (Japan)	Hongxun Chen (China)	Julie Chen (US)
Jusuke Hidaka (Japan)	Kevin W. Powers (US)	Lifeng Zhang (US)
Mamoru Senna (Japan)	Mark Jones (Australia)	Michael Stintz (Germany)
Mingwei Gao (Australia)	Mojtaba Ghadiri (UK)	Pong K. Paik (Korea)
Pradip (India)	Qianqiu Zhao (US)	R. H.Wohibier (Germany)
Reg. Davies (US)	Reiner Grochowski (Germany)	Ren. Xu (US)
Ulrich Teipel (Germany)	Wiwut T. (Thailand)	Yuansheng Cui (China)
Yutaka Tsuji (Japan)	Zhenghe Xu (Canada)	Zhixian Jin (China)

Background

The spread of current global financial crisis has drawn a large number of businesses, including the industries related to powder production and processing, into a sharp deterioration. Since the government has taken plenty of measures to help enterprises out of the plight, industries should also analyze the strong and weak points, adjust the product mix, and seek new ways to lower the cost of production. Under these circumstances, the inter-corporation, inter-industry and international communication becomes much more necessary.

On the other hand, with global shortage of resources and energy, it is urgent to save energy, reduce resource consumption and boost comprehensive recycling. The improvement of powder technology and equipments, such as pulverization, sieving, separation, mixing, drying, transportation, storage and packaging, plays an important role in the resources and energy saving.

Aiming at expanding international cooperation and complying the government's policies of saving energy, reducing consumption and developing recycling economy, China Building Materials Federation and China Powder Technology Association will jointly sponsor '2009 China International Powder Technology & Equipment Exhibition, 2009 China International Industrial Powder Raw Materials Exhibition', as well as '2009 China International Powder Technology & Application Forum' and 2009 National Conference on Powder Processing and Application.

The 2009 China International Powder Technology & Application Forum will mainly focus on the nanotechnology and new materials, comprehensive utilization of resources, energy saving in powder processing, as well as the advanced grinding, storage and transportation technologies and facilities.

The Paper and Speech are Invited on the Following Topics

- A. Advanced Grinding Technology and the Enlargement of Application Range**
- B. Bulk Materials Storage and Transportation Technology and Facilities**
- C. Novel Bio-materials and Wood Powder**
- C. Energy Saving about Large-size Grinding Equipment and Wearable Materials**

Submit of the Paper

Full paper or PPT should be emailed to Miss Su, powder@tsinghua.edu.cn, before March 20th, and we will distribute the printed material and CD during the Forum. Papers submitted to the forum will be published by *Advanced Materials Research* (Ei index). The proceedings of 2008 IFPT have been published, and you may visit <http://www.scientific.net/> for more details.

Schedule

2009	March 29 th	30 th	31 st	April 1 st	2 nd	3 rd
Exhibition		Preparation		Exhibition Day		
International Forum on Powder Technology and Application	Registra-tion	Forum At Tsinghua University		Technical Tour		
International Technology Transfer and Investment				2009 National Conference on Powder Processing and Application		
				Beijing Exhibition Center in the center of Beijing City		

Sponsors

China Building Materials Federation
China Powder Technology Association
International Federation of Measurement & Control of Granular Materials

Organizers

China Powder Technology Association
Research Institute of Energy and Eco materials, Tsinghua University
Powder Engineering Institute, Xi'an Architecture Science and Technology University

Oversea Supporters

Australia Society of Bulk Solid Handling
Beckman Coulter, Inc.
Centre for Bulk Solids & Tunra Bulk Solids, University of Newcastle
DuPont Engineering Research & Technology-Particle Technology Group
Nanomanufacturing Center of Excellence U Mass Lowell
National Nanotechnology Center, Thailand
Particle Engineering Research Center, University of Florida
Technology Transfer Center of Massachusetts
The Association of Powder Processing Industry & Engineering, Japan
The Society of Powder Technology, Japan
The Powder/Bulk Portal Bulk-online
Vogel Transtech Publications, Powder Handling & Processing

Domestic Supporters:

China Coating Industry Association
The Chinese Society for Metals, Powder Metallurgy Branch
China Plastic Processing Industry Association
China Inorganic Salt Industry Association
China Rubber Society
China Feed Industry Association
China Agriculture Society
China Battery Industry Association
China Association of Resource Comprehensive Utilization
China High-Tech Industry Promotion Association

China Machinery Industry Association
China Pesticide Industry Association
China Cement Association
China Ceramic Society
World Federation of Chinese Medicine Societies, Herb Branch

General Program:

March 29th, Registration all day
March 30th, Opening ceremony, Key note speeches
March 31st, Speech and Discussions
April 1st, Visiting the Exhibition and Technical Tour (Social Activities)

Registration

Fee: \$300 per person for delegate. Please note that Registration Fees do not include payment for hotel accommodation.

Time: March 29th **Place:** the gate hall of Unisplendour International Center

Account Information

Name of Account: TSINGHUA UNIVERSITY
Account No. 00047108094001
Account Opening Bank: The Bank of China, Head Office
Address: No.1, Fuxingmen Nei Avenue, Beijing, PRC, 100818
Swift Code: BKCHCNBJ
Telex No.:22254 BCHO CN
MESSAGE: Powder Forum, Dept. of Material, Miss Su, Tel.: 010-62781144

Hotel

Unisplendour International Center
It is in front of the main gate of Tsinghua University
For more information please visit: www.uniscenter.com

If you want to have a room in this hotel, let us know, there will be a discount for the guest of Tsinghua University.

Visa

Please contact your local Chinese Embassy first, ask what documents are needed to apply the visa. We can make it as soon as possible.

Further Information

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Tour to visit other place

If you want to visit other place in China, we can help you to contact with China International Travel Service Beijing, or you can visit its website: www.citsbj.com/english/ for more details.

Registration form

2009 International Forum on Powder Technology and Application

Title: _____ First name: _____ Surname: _____

Company /Institute: _____

Correspondence address: _____

Telephone: _____ Fax: _____

E-mail: _____

Paper want to be presented at the Forum

Fax to 0086-10-62791258, or email to gaigs@tsinghua.edu.cn

Your Paper's Title Starts Here: Please Center

use Helvetica (Arial) 14

FULL First Author^{1, a}, FULL Second Author^{2, b} and Others^{3, c}

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Introduction

All manuscripts must be in English. Please keep a second copy of your manuscript in your office (just in case anything gets lost in the mail). When receiving the manuscript, we assume that the corresponding authors grant us the copyright to use the manuscript for the book or journal in question. Should authors use tables or figures from other Publications, they must ask the corresponding publishers to grant them the right to publish this material in their paper.

Use *italic* for emphasizing a word or phrase. Do not use boldface typing or capital letters except for section headings (cf. remarks on section headings, below). Use a laser printer, not a matrix dot printer.

Organization of the Text

Section Headings. The section headings are in boldface capital and lowercase letters. Second level headings are typed as part of the succeeding paragraph (like the subsection heading of this paragraph).

Page Numbers. Do *not* print page numbers: Please number each sheet toward the middle near the bottom (outside the typing area) with a soft pencil.

Tables. Tables (refer with: Table 1, Table 2, ...) should be presented as part of the text, but in such a way as to avoid confusion with the text. A descriptive title should be placed above each

table. The caption should be self-contained and placed *below or beside* the table. Units in tables should be given in square brackets [meV]. If square brackets are not available, use curly {meV} or standard brackets (meV).

Special Signs. for example , $\alpha \gamma \mu \Omega () \geq \pm \bullet \Gamma \{11\bar{2}0\}$ should always be written in with the fonts Times New Roman or Arial

Figures. Figures (refer with: Fig. 1, Fig. 2, ...) also should be presented as part of the text, leaving enough space so that the caption will not be confused with the text. The caption should be self-contained and placed *below or beside* the figure. Generally, only original drawings or photographic reproductions are acceptable. Only very good photocopies are acceptable. Utmost care must be taken to *insert the figures in correct alignment with the text*. Half-tone pictures should be in the form of glossy prints. If possible, please include your figures as graphic images in the electronic version. For best quality the pictures should have a resolution of 300 dpi(dots per inch).

Color figures are welcome for the online version of the journal. Generally, these figures will be reduced to black and white for the print version. The author should indicate on the checklist if he wishes to have them printed in full color and make the necessary payments in advance.

Equations. Equations (refer with: Eq. 1, Eq. 2, ...) should be indented 5 mm (0.2"). There should be one line of space above the equation and one line of space below it before the text continues. The equations have to be numbered sequentially, and the number put in parentheses at the right-hand edge of the text. Equations should be punctuated as if they were an ordinary part of the text. Punctuation appears after the equation but before the equation number, e.g.

$$c^2 = a^2 + b^2. \quad (1)$$

Literature References

References are cited in the text just by square brackets [1]. (If square brackets are not available, slashes may be used instead, e.g. /2/.) Two or more references at a time may be put in one set of brackets [3,4]. The references are to be numbered in the order in which they are cited in the text and are to be listed at the end of the contribution under a heading *References*, see our example below.

Summary

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References

[1] Dj.M. Maric, P.F. Meier and S.K. Estreicher: Mater. Sci. Forum Vol. 83-87 (1992), p. 119

- [2] M.A. Green: *High Efficiency Silicon Solar Cells* (Trans Tech Publications, Switzerland 1987).
- [3] Y. Mishin, in: *Diffusion Processes in Advanced Technological Materials*, edited by D. Gupta Noyes Publications/William Andrew Publishing, Norwich, NY (2004), in press.
- [4] G. Henkelman, G. Johansson and H. Jónsson, in: *Theoretical Methods in Condensed Phase Chemistry*, edited by S.D. Schwartz, volume 5 of *Progress in Theoretical Chemistry and Physics*, chapter, 10, Kluwer Academic Publishers (2000).
- [5] R.J. Ong, J.T. Dawley and P.G. Clem: submitted to *Journal of Materials Research* (2003)
- [6] P.G. Clem, M. Rodriguez, J.A. Voigt and C.S. Ashley, U.S. Patent 6,231,666. (2001)
- [7] Information on <http://www.weld.labs.gov.cn>